PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HUANXIN LIU	12/01/2011

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13310624

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NAME OF SUBMITTER:	Michael J. Ram

Total Attachments: 1
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Docket No. 803-2F-019
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ASSIGNMENT

I, **Huanxin Liu,** citizen of Beijing, China, having an address of 18 Wen Chang Road, Economic-Technological Development Area, Daxing District, Beijing 100176, P.R. China, (hereinafter "Inventor"), represent that I have invented improvements in a new and useful METHOD OF FABRICATING A SEMICONDUCTOR DEVICE (hereinafter the "Invention") set forth in China Patent Application No. 201110227768.9, for which I have executed an application for Letters Patent of the United States of America on the same day as my execution of this Assignment.

SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION, is a Beijing corporation, has a place of business at 18 Wen Chang Road, Economic-Technological Development Area, Daxing District, Beijing 100176, P.R. China, and desires to acquire the entire right, title and interest in and to the invention, application and Letters Patent to be granted and issued thereon.

For valuable consideration, the receipt and legal sufficiency of all of which I acknowledge, I have sold and do hereby sell, assign, transfer and set over unto SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION, its successors and assigns, the entire right, title and interest in and to the invention and all improvements thereon, in and to the application for Letters Patents thereon, in and to applications pertaining to or based upon the invention and application, including divisional and continuing applications and continuations-in-part, and in and to any and all Letters Patent which may be granted and issued on the invention and applications, or any of them, in the United States of America, its territories and possessions, and in all countries foreign thereto, together with and including all priority rights based upon any and all applications in the United States of America covered by this Assignment.

I also agree that I will, at the request of SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION, execute any and all applications for Letters Patent for the invention, execute any and all other papers and documents and do all other and further lawful acts that SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION may deem necessary or desirable to obtain Letters Patent on the invention, to secure the grant of such Letters Patent and to protect and vest in SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION the undivided interests in the right, title and interest in the invention, applications and Letters Patent.

I also authorize and empower SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION, its successors and assigns to apply for and obtain, in its or their own names, Letters Patent for the invention before competent International Authorities and in any and all countries foreign to the United States in which applications for Letters Patent can be so made or letters patent so obtained.

Dated 2011-12-1

HUANXIN LIU
HUANXIN LIU

WITNESS 涂火金

(Type or print name below line)

WITNESS 刘佳磊

(Type or print name below line)